

## GENERAL DESCRIPTION

The ME4948 is the Dual N-Channel logic enhancement mode power field effect transistors, using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on state resistance. These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and low in-line power loss that are needed in a very small outline surface mount package.

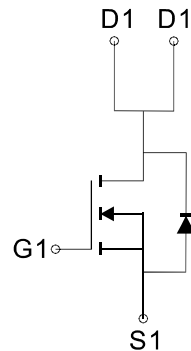
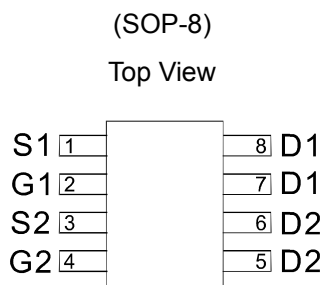
## FEATURES

- $R_{DS(ON)} \leq 53 \text{ m}\Omega @ V_{GS}=10\text{V}$
- $R_{DS(ON)} \leq 78 \text{ m}\Omega @ V_{GS}=4.5\text{V}$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

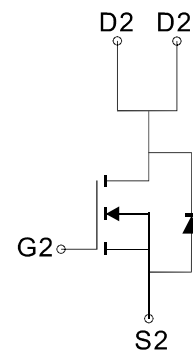
## APPLICATIONS

- Power Management in Note book
- DC/DC Converter
- Load Switch
- LCD Display inverter

## PIN CONFIGURATION



N-Channel MOSFET



N-Channel MOSFET

Ordering Information: ME4948 (Pb-free)

ME4948-G (Green product-Halogen free)

## Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage		$V_{DSS}$	60	V	
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V	
Continuous Drain Current (Tj=150°C)	$T_A=25^\circ\text{C}$	$I_D$	4.5	A	
	$T_A=70^\circ\text{C}$		3.6		
Pulsed Drain Current		$I_{DM}$	18	A	
Single Pulse Avalanche Energy (L=0.1mH, IAS=8A)		EAS	3.2	mJ	
Maximum Power Dissipation	$T_A=25^\circ\text{C}$	$P_D$	1.67	W	
	$T_A=70^\circ\text{C}$		1.07		
Operating Junction Temperature		$T_J$	-55 to 150	°C	
Thermal Resistance-Junction to Ambient *		$R_{\theta JA}$	Steady State	75	°C/W

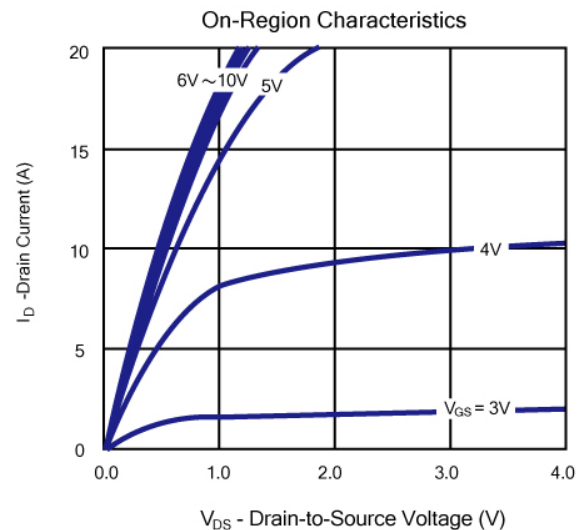
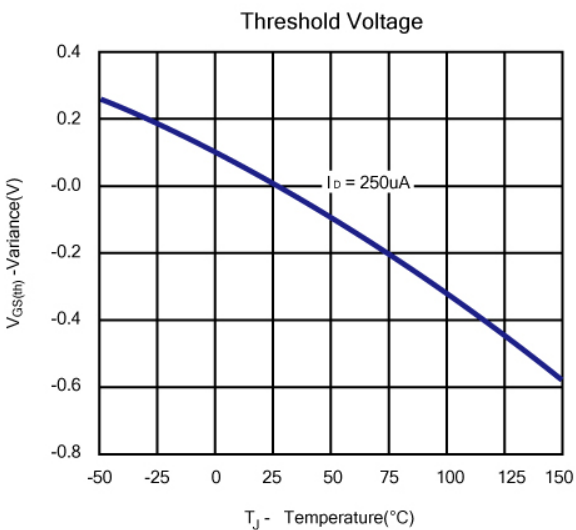
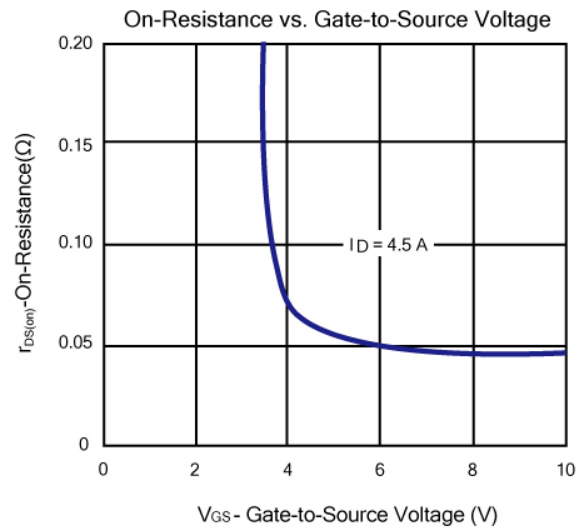
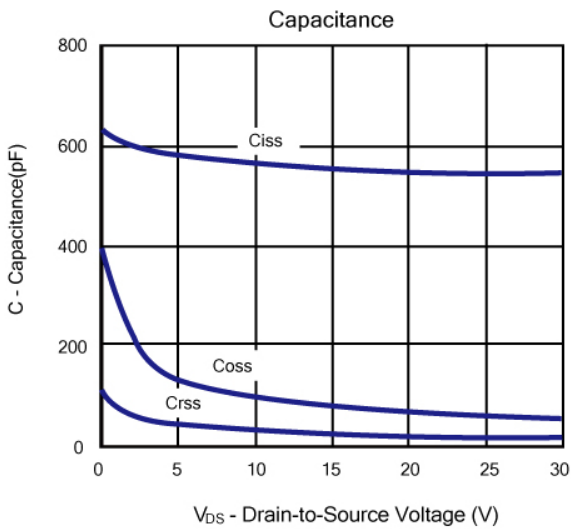
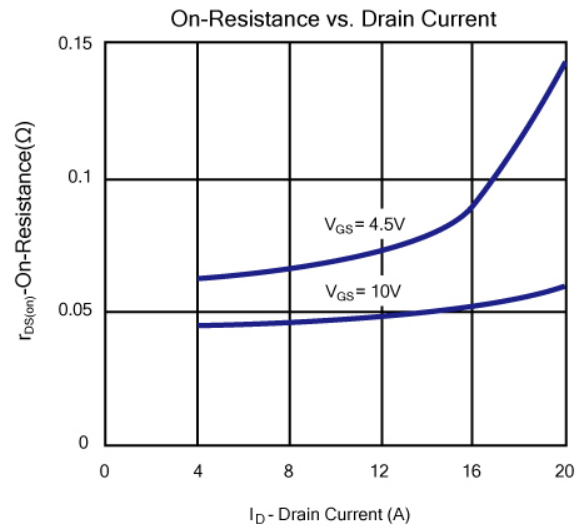
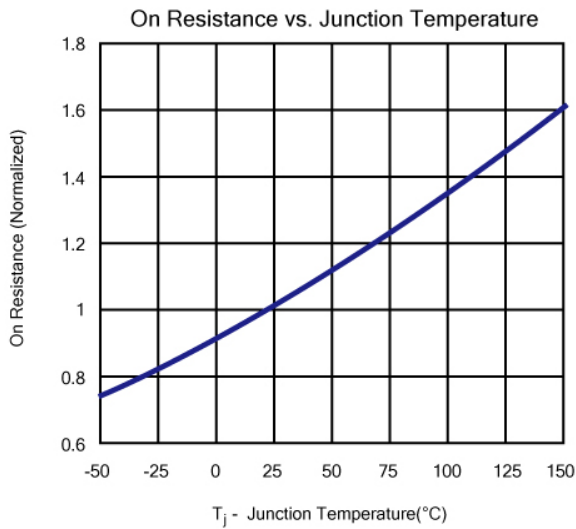
\* The device mounted on 1in<sup>2</sup> FR4 board with 2 oz copper

Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250 μA	60			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1		3	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			10	
R <sub>DS(ON)</sub>	Drain-Source On-Resistance <sup>a</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> = 4.5A		45	53	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> = 3.6A		60	78	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =2.0A, V <sub>GS</sub> =0V		0.8	1.2	V
<b>DYNAMIC</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =4.5A		16		nC
Q <sub>g</sub>	Total Gate Charge			8.7		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =30V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.5A		4.4		
Q <sub>gd</sub>	Gate-Drain Charge			3.6		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz		560		pF
C <sub>oss</sub>	Output Capacitance			73		
C <sub>rss</sub>	Reverse Transfer Capacitance			22		
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V, R <sub>L</sub> =15Ω, V <sub>GEN</sub> =10V, R <sub>G</sub> =1Ω		12		ns
t <sub>r</sub>	Turn-On Rise Time			16		
t <sub>d(off)</sub>	Turn-Off Delay Time			34		
t <sub>f</sub>	Turn-Off Fall Time			4		

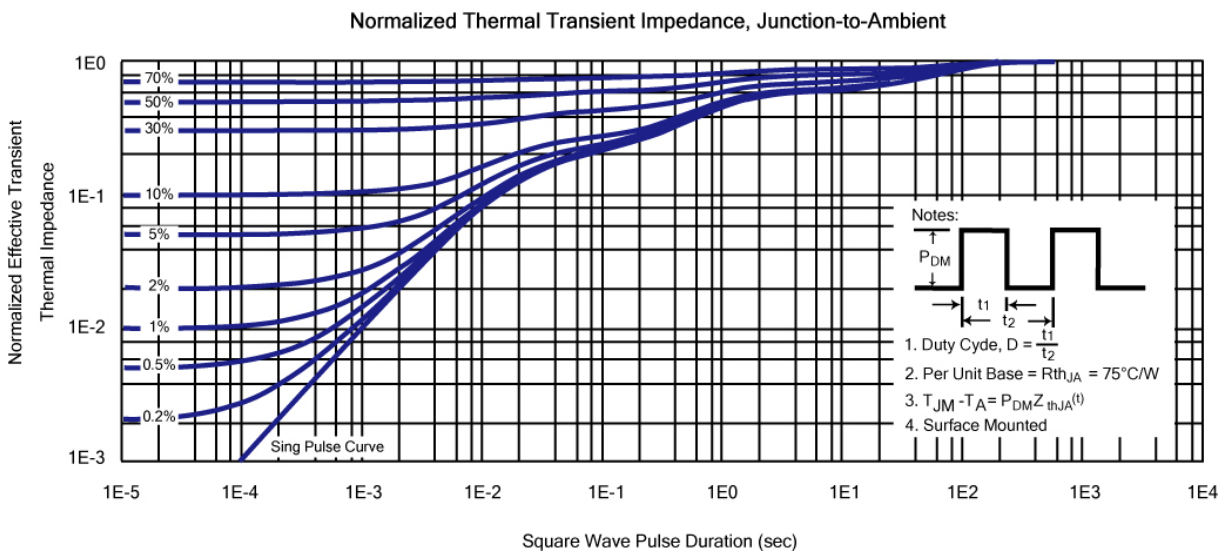
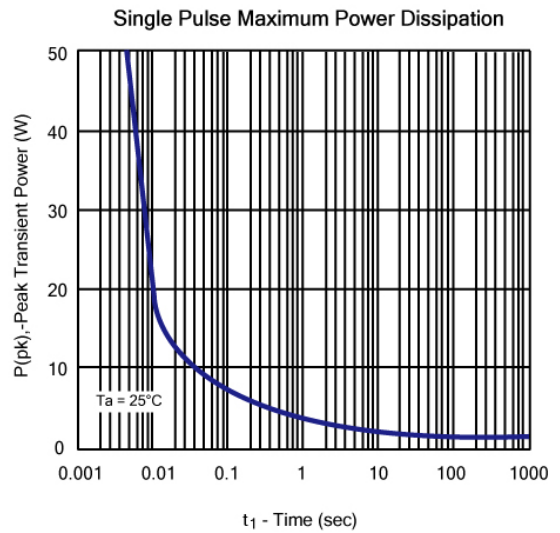
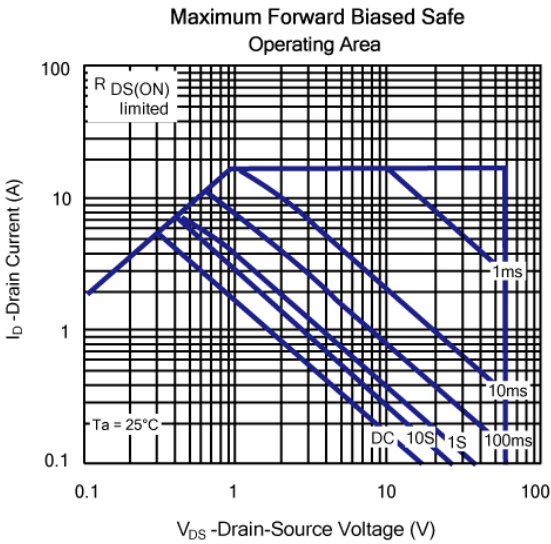
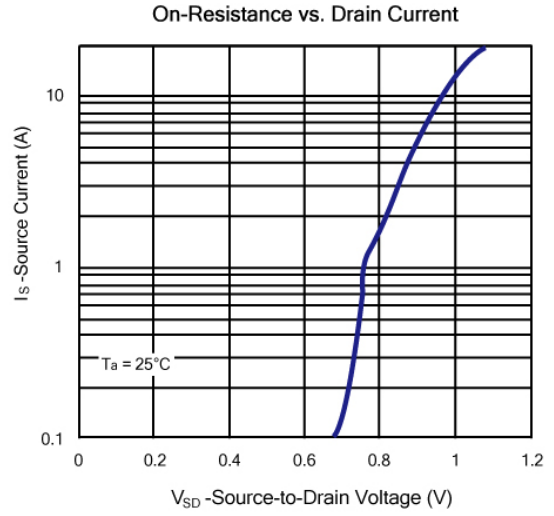
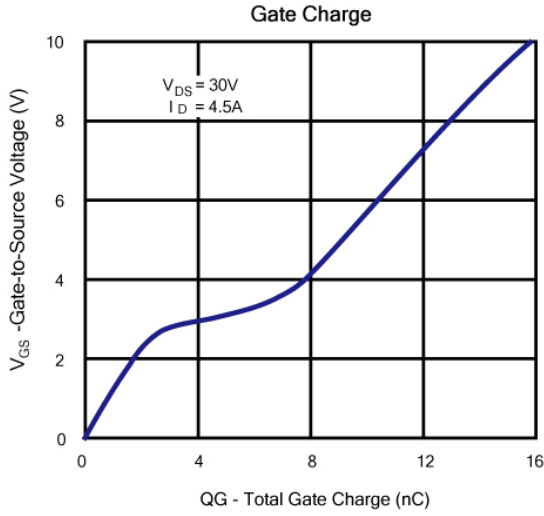
Notes: a. Pulse test: pulse width ≤ 300us, duty cycle ≤ 2%, Guaranteed by design, not subject to production testing.

b. Matsuki reserves the right to improve product design, functions and reliability without notice.

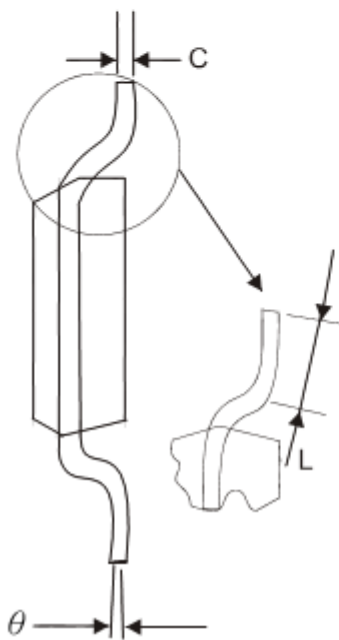
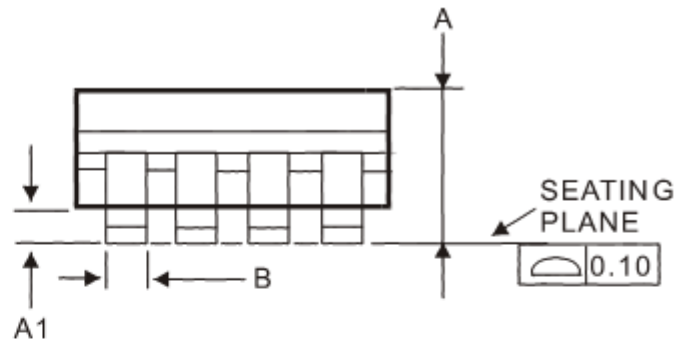
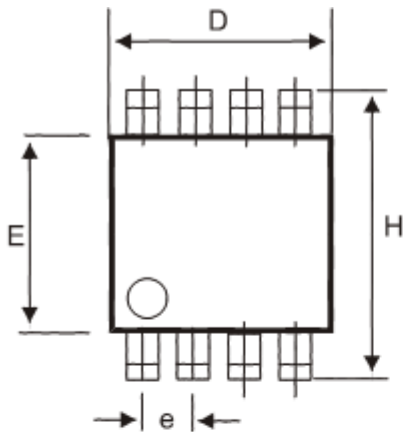
## Typical Characteristics (T<sub>J</sub> = 25°C Noted)



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**SOP-8 Package Outline**



DIM	MILLIMETERS (mm)	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
L	0.40	1.25
$\theta$	0°	7°

Note: 1. Refer to JEDEC MS-012AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per side.